

Layer	Stack up	Supplier	Supplier Description	Description	Type	Processed Thickness	εr	Copper Layer Type		
1		Polar Samples	SM/001	Liquid Photolimageable Mask	SolderMask	25.400	4.000			
		Polar Samples	FO/001	Copper Foil	Copper	50.000		Signal		
		Isola	FR408HR	2116	Prepreg	108.000	3.720			
2		Polar Samples	FO/001	Copper Foil	Copper	18.000		Plane		
		Isola	FR408HR	1080	Prepreg	74.613	3.500			
		Isola	FR408HR	1080	Prepreg	74.613	3.500			
3						17.780		Signal		
		Isola	FR408HR	2-2116	Core	254.000	3.720			
						17.780		Plane		
4		Isola	FR408HR	1080	Prepreg	74.168	3.500			
		Isola	FR408HR	1080	Prepreg	74.168	3.500			
						17.780		Signal		
5		Isola	FR408HR	2-1080	Core	152.400	3.540			
						17.780		Signal		
6		Isola	FR408HR	1080	Prepreg	74.168	3.500			
		Isola	FR408HR	1080	Prepreg	74.168	3.500			
						17.780		Plane		
7		Isola	FR408HR	2-2116	Core	254.000	3.720			
						17.780		Signal		
8		Isola	FR408HR	1080	Prepreg	74.613	3.500			
		Isola	FR408HR	1080	Prepreg	74.613	3.500			
						17.780		Plane		
9		Polar Samples	FO/001	Copper Foil	Copper	18.000		Plane		
		Isola	FR408HR	2116	Prepreg	108.000	3.720			
		Polar Samples	FO/001	Copper Foil	Copper	50.000		Signal		
10		Polar Samples	SM/001	Liquid Photolimageable Mask	SolderMask	25.400	4.000			

Copper Thickness = 242.680 | Dielectric Thickness = 1471.522 | Solder Mask Thickness = 50.800 | Stack Up Thickness = 1714.202 | Stack Up Thickness with Soldermask = 1765.002

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Lower Trace Width (W1)	Upper Trace Width (W2)	Trace Separation (S1)	Ref. Plane 1 in Layer	Substrate 1 Height (H1)	Ref. Plane 2 in Layer	Substrate 2 Height (H2)	Target Impedance	Tol (+/- %)	Calculated Impedance	
	1	Coated Microstrip 1B	1	187.000	182.000	0.000	2	108.000	0	0.000	50.000	20.000	0.000	
	2	Edge Coupled Coated Microstrip 1B	1	139.000	134.000	201.000	2	108.000	0	0.000	100.000	20.000	0.000	
	3	Offset Stripline 1B1A	3	149.000	144.000	0.000	2	254.000	4	167.010	50.000	20.000	0.000	
	4	Edge Coupled Offset Stripline 1B1A	3	126.000	121.000	204.000	2	254.000	4	167.010	100.000	20.000	0.000	

StackName: 192102A-DPC2-XSPS	Version:	Revision:	Modification:	Date of Revision:	Editor
Date: 22.04.2020	Associated Documents:	A	Initial	07.11.2019	NL84
Author: NL84		B	min. 150um Tracks	07.11.2019	NL84
Department: 8422		C	0-Series Production	27.04.2020	NL84
Site:					

Structure Image	Impedance ID	Structure Name	Impedance Signal Layer	Lower Trace Width (W1)	Upper Trace Width (W2)	Trace Separation (S1)	Ref. Plane 1 in Layer	Substrate 1 Height (H1)	Ref. Plane 2 in Layer	Substrate 2 Height (H2)	Target Impedance	Tol (+/- %)	Calculated Impedance	
	5	Offset Stripline 2B1A	5	159.000	154.000	0.000	4	166.120	7	152.400	50.000	20.000	0.000	
	6	Edge Coupled Offset Stripline 2B1A	5	132.000	127.000	208.000	4	166.120	7	152.400	100.000	20.000	0.000	
	7	Edge Coupled Offset Stripline 2B1A	6	132.000	127.000	208.000	4	166.120	7	152.400	100.000	20.000	0.000	
	8	Offset Stripline 2B1A	6	159.000	154.000	0.000	4	166.120	7	152.400	50.000	20.000	0.000	
	9	Edge Coupled Offset Stripline 1B1A	8	126.000	121.000	204.000	7	254.000	9	167.010	100.000	20.000	0.000	
	10	Offset Stripline 1B1A	8	149.000	144.000	0.000	7	254.000	9	167.010	50.000	20.000	0.000	
	11	Edge Coupled Coated Microstrip 1B	10	139.000	134.000	201.000	9	108.000	0	0.000	100.000	20.000	0.000	
	12	Coated Microstrip 1B	10	187.000	182.000	0.000	9	108.000	0	0.000	50.000	20.000	0.000	

Drill Image	1st Layer	2nd Layer	Column Position	Drill Type	Fill Type	Minimum Size	
	1	2	2	Laser PTH	None	0.120	
	1	10	1	Mechanical PTH	None	0.200	
	10	9	2	Laser PTH	None	0.120	

Notes

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